

ABSTRACT OF THE DISCLOSURE

A multilayer circuit board formed by integrally laminating a plurality of printed wiring boards in a multilayer structure so as to provide air gaps therebetween. An insulating layer is formed on each of both surfaces of a metal core substrate having through-hole forming apertures and a printed wiring layer is formed on the each insulating layer. Metal projections integrally formed on the metal core substrate serve as bonding electrodes between the adjacent wiring boards in the multilayer structure. The width of the air gap provided between the adjacent wiring boards is determined by the height of the metal projections.

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